

L Number	Hits	Search Text	DB	Time stamp
7	12	processor and package and substrate and solder near resist and mold\$3 near compound	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT	2004/07/22 11:44
8	24	("4426341" "4437229" "4510673" "4554126" "4585931" "4787143" "5172053" "5175425" "5181097" "5197650" "5256578" "5645787" "5654204" "5872398" "5998243" "6001672" "6021380" "6052798" "6090644" "6106259" "6111324" "6117382" "6192457" "6415977" "2001/0004002").PN.	USPAT	2004/07/22 11:02
9	29	("5030113" "5044912" "5101322" "5133118" "5241133" "5261593" "5276418" "5328087" "5349500" "5428190" "5445308" "5502889" "5556293" "5572405" "5611705" "5614443" "5615477" "5620928" "5635671" "5637916" "5652185" "5661088" "5663593" "5668405" "5680746" "5681757" "5688584" "5696027" "5696666").PN.	USPAT	2004/07/22 11:04
10	14	("4598337" "4688152" "4866506" "5130889" "5239198" "5241133" "5262351" "5287247" "5296738" "5309322" "5384689" "5506383" "5541450" "5631807").PN.	USPAT	2004/07/22 11:07
11	2	processor and package and solder near resist and mold\$3 near compound and (438/901; 29/843 ; 29/844 ; 165/80.3 ; 165/185 ; 174/16.3 ; 174/252 ; 174/258 ; 174/260 ; 257/675 ; 257/676 ; 257/705-707 ; 361/386, 361/401 ; 361/389 ; 361/421 ; 361/403 ; 361/408 ; 361/410 ; 361/414 ; 361/400 ; 361/702 ; 361/704 ; 361/707 ; 361/709 ; 361/723 ; 361/760 ; 361/762 ; 361/767 ; 361/778).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/22 11:20
12	5	("5389497" "5500315" "5903041" "6137634" "6207346").PN.	USPAT	2004/07/22 11:18
13	3	processor and package and solder near resist and mold\$3 near compound and (174/255; 174/260 ; 361/748-751).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/22 11:22

14	5	Manepalli near Rahul .inv.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/22 11:21
15	232	Jiang near Tongbi .inv.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/22 11:22
16	232	Jiang near Tongbi .inv.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/22 11:42
17	0	Jiang near Tongbi .inv. and processor near IC	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/22 11:42
18	0	Jiang near Tongbi .inv. and integrate adj circuit near package	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/22 11:43
19	0	Jiang near Tongbi .inv. and integrate adj package	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/22 11:44
20	168	Jiang near Tongbi .inv. and package	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/22 11:44
21	23	method near (processor or package) and substrate and solder near resist and mold\$3 near compound	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/22 11:46
22	0	"method for making package" and substrate and solder near resist and mold\$3 near compound	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/22 11:46
23	0	"method for making package" and solder near resist and mold\$3 near compound	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/22 11:46

24	27	IC and solder near resist and mold\$3 near compound	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/22 11:48
25	6	IC and solder near resist and mold\$3 near compound and (29/840; 29/841 ; 29/832 ; 257/668 ; 257/778 ; 257/676 ; 438/118 ; 438/126 ; 438/336 ; 438/200 ; 174/255 ; 174/260).cccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/22 11:48
26	6	IC and solder near resist and mold\$3 near compound and (29/840; 29/841 ; 29/832 ; 257/668 ; 257/778 ; 257/676 ; 438/118 ; 438/126 ; 438/336 ; 438/200 ; 174/255 ; 174/260).cccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/22 11:48
27	12	("5701013" "5712707" "5757507" "5789118" "5953128" "5976740" "6023338" "6031614" "6048755" "6063530" "6068954" "6441504" "2002/0020908" "2002/0148897").PN.	USPAT	2004/07/22 11:49

	Title	Current OR
1	Solder resist opening to define a combination pin one indicator and fiducial	29/840
2	Solder resist opening to define a combination pin one indicator and fiducial	29/841
3	Solder resist opening to define a combination pin one indicator and fiducial	174/260
4	Method of making a semiconductor device having an opening in a solder mask	29/840
5	Method of production of semiconductor device	29/832
6	Method for making a conductive film composite	29/846

	Current XRef	Retrieval Classif
1	29/832; 29/834; 29/843	29/832; 29/840
2	29/834; 29/840; 29/854; 29/855	29/840; 29/841
3	29/832; 29/840	174/260; 29/832; 29/840
4	174/255; 174/260; 29/832; 29/841	174/255; 174/260; 29/832; 29/840; 29/841
5	174/260; 228/179.1; 228/180.21; 257/E21.514; 29/840; 29/846	174/260; 29/832; 29/840
6	174/255; 174/261; 29/845	174/255